



Solution brief

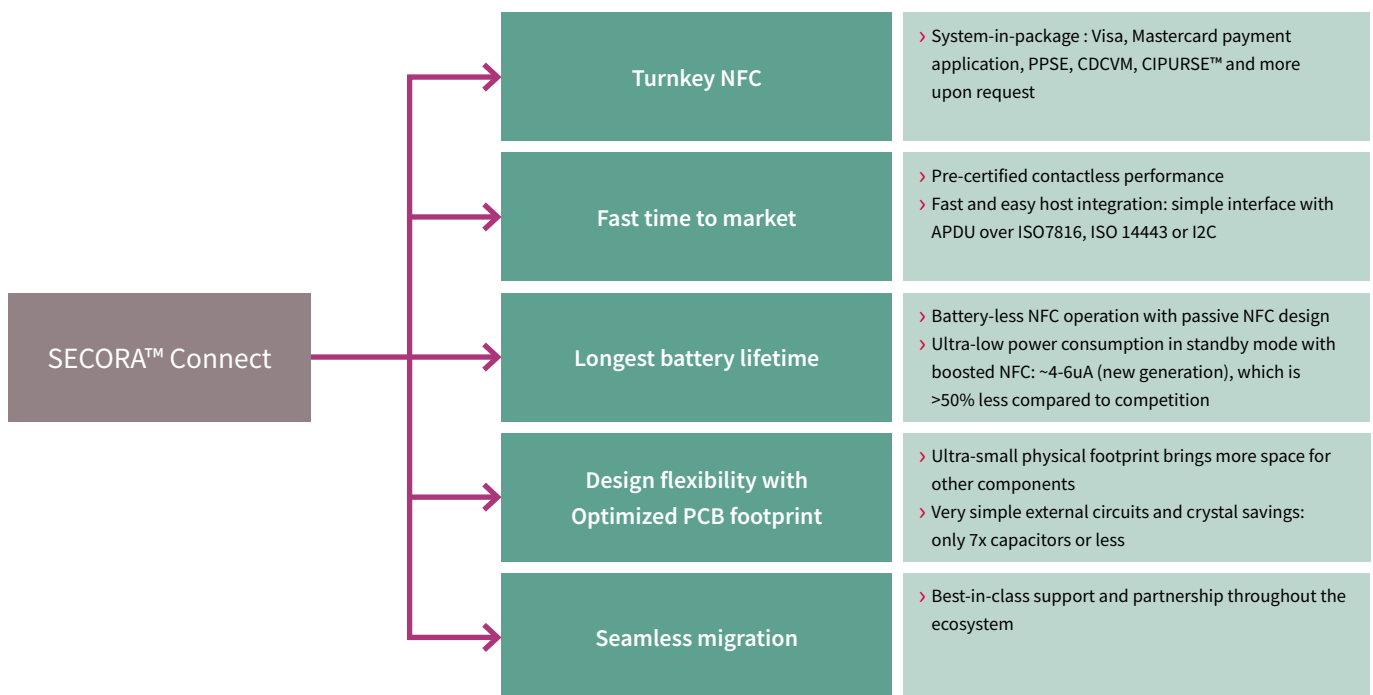
SECORA™ Connect

Empowering Smart Wearables and IoT Devices with NFC Security Applications and more

The future of payment is contactless. Responding to the growing consumer demand for smart devices and wearables, OEMs are increasingly offering payment and other popular security-relevant applications such as ticketing and access control based on contactless technologies. This presents OEMs with new security and performance challenges as they strive to meet the standards mandated by EMVCo or comply with payment network certification requirements, for instance. Rising device integration, power efficiency and actual service enablement present additional pressure points.

Infineon addresses these challenges with a dedicated product family of turnkey security solutions for battery-powered smart devices. SECORA™ Connect includes all relevant components (Secure Element, operating system with payment, transport ticketing and access applications, antenna for contactless communication, turnkey packaging) plus complementary enablement services delivered by Infineon or its ecosystem partners.

SECORA™ Connect provides OEMs with the following benefits:



SECORA™ Connect

Enables the efficient and streamlined integration of security applications for seamless connection of wearables and other IoT devices to the digital world.

Portfolio overview

Product offering



SECORA™ Connect boosted SiP



SECORA™ Connect boosted MCP



SECORA™ Connect passive NFC



SECORA™ Connect embedded

Main benefit with examples

All-in-one off-the-shelf

Standard wearable

Right-fit customized design

Metal housing wearable, ring

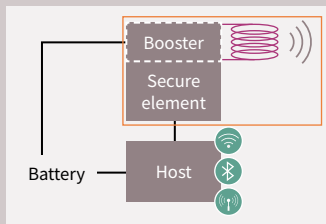
Zero power during transactions

Wristband or key fob

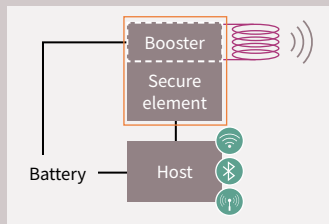
Trusted anchor to store payment credentials (tokens)

Cars, voice assistant

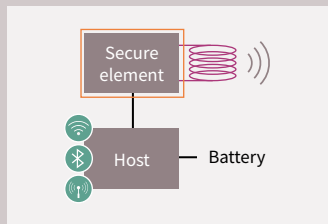
System architecture and package specification



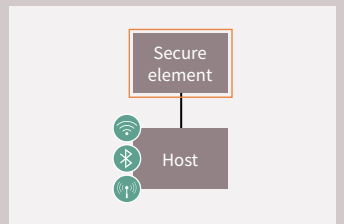
5 x 5 mm² LGA package



4 x 4mm² MCP VQFN32



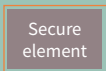
4.2 x 4.0 mm² PG USON-8-3



4.2 x 4.0 mm² PG USON-8-3

SLJ52W Secure Element Generation Highlights

System-on-Chip



- > Operating system: Java Card 3.0.4, GlobalPlatform 2.2.1
- > Payment Applets: M/Chip Mobile Application v1.1.3, Visa Mobile Payment Application v1.4.4.0
- > Optional: CIPURSE™, Calypso, CDCVM
- > Ready for: FIDO U2F, FIDO 2.0
- > Supports Decentralized Secure Element Management (DSEM) and remote provisioning
- > Host communication via ISO/IEC 7816-3 or I2C

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